



info@okos.com

# VUE 250-P NEXGEN SCANNING ACOUSTIC MICROSCOPE

Semiconductor Package Failure Analysis voids · disbonds · cracks · delamination · internal defects

#### **Customer Interface**

Dual 22" HD LED Monitors

#### **Fixtures**

Open Tank Bed

#### Instrumentation

Digital Pulser Receiver Digitizer (Max 4 GHz)

#### **User Experience Elements**

HD LED Lighting Stainless Steel Tank

#### **Maintenance Free Scan Axis**

Motor: Linear Servo
Max Velocity: 500 mm/s
Accuracy & Repeatability: +/- 1.0 micron
Scan Envelope: 322.6 mm

#### **Low Maintenance Step Axis:**

Step Envelope 136 mm

#### **Low Maintenance Focus Axis:**

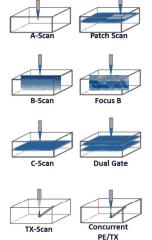
Focus Envelope 35 mm

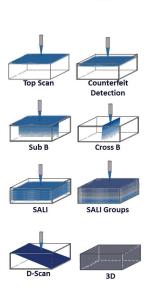
#### **Dimensions:**

700 mm x 560 mm x 470 mm (W/D/H) 81 kg

## **Full Jedec Tray Inspection**









# VUE 250-P NEXGEN SCANNING ACOUSTIC MICROSCOPE

#### **Included Software Modes:**

- Basic (user friendly)
- Advanced (detailed analysis)
- Production (automated scanning)
- Off-line Analysis (virtual scanning)





### **OKOS Digital Imaging System (ODIS)**



VUE 250-P imaging power surpasses modern standards delivering premium FA Lab features to semiconductor fabrication facilities. ODIS is the latest Acoustic Microscopy software with rich technical content built on current platforms and industry feedback. It includes both time domain and frequency domain imaging in real-time. Advanced analysis is provided through quantitative tools for measurement and classification of parts.

The Analysis version of ODIS allows non-scanning computers to virtually scan, view, and analyze data for simultaneous real-time analysis or post collection review. Supplied with your choice of Windows 7 or 10.

· Counterfeit Detection · Product Inspection

· Product Reliability

· Quality Control

· Process Validation

· Failure Analysis

· Vendor Oualification · R&D

### **Application Specific Transducers**

for the highest quality resolution. Multiple transducer design for enhanced scan capability.





3D Imaging





